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Intel® Core™ i3-2130 Processor (3M Cache, 3.40 GHz)

Specifications: Essentials Performance Memory Specifications Graphics Specifications **Expansion Options** Package Specifications Advanced Technologies Intel® Data Protection Technology Intel® Platform Protection Technology

Product Images Ordering / sSpecs / Steppings

Compatible Products

Specifications Essentials Status End of Life Q3'11 Launch Date Q3'2013 Expected Discontinuance Processor Number i3-2130 3 МВ Intel® Smart Cache 5 GT/s DMI 64-bit Instruction Set SSE4.1/4.2, AVX Instruction Set Extensions Q No Embedded Options Available Lithography 32 nm Recommended Customer Price BOX: \$117.00 Datasheet Link Performance

2 # of Cores # of Threads

Processor Base Frequency 3.4 GHz TDP 65 W Memory Specifications Max Memory Size (dependent on memory type) 32 GB

DDR3 1066/1333

Memory Types Max # of Memory Channels 21 GB/s Max Memory Bandwidth Graphics Specifications Intel® HD Graphics 2000 Processor Graphics * Graphics Base Frequency 850 MHz Graphics Max Dynamic Frequency 1.1 GHz Q Intel® Quick Sync Video Yes Intel® InTru™ 3D Technology Intel® Insider™ Q No Intel® Wireless Display Intel® Flexible Display Interface (Intel® FDI) Intel® Clear Video HD Technology # of Displays Supported * 2 Expansion Options

16 Max # of PCI Express Lanes Package Specifications Max CPU Configuration 1 69.1°C TCASE Package Size 37.5mm x 37.5mm Sockets Supported FCLGA1155 Low Halogen Options Available See MDDS

2.0

PCI Express Revision

 Advanced Technologies Intel® Turbo Boost Technology * No Intel® vPro Technology * Q No Intel® Hyper-Threading Technology * Q Yes Intel® Virtualization Technology (VT-x) * Intel® Virtualization Technology for Directed I/O No (VT-d) * Intel® VT-x with Extended Page Tables (EPT) * Intel® 64 * Q Idle States Enhanced Intel SpeedStep® Technology Q Thermal Monitoring Technologies Intel® Fast Memory Access Intel® Flex Memory Access Intel® Identity Protection Technology * Intel® Data Protection Technology Q No AES New Instructions

 Intel® Platform Protection Technology Trusted Execution Technology * Execute Disable Bit *

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Q No

Refer to Datasheet for formal definitions of product properties and features.

For benchmarking data see http://www.intel.com/performance.

classification of any item at the time of export.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability. Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact

OEM for the BIOS that includes the latest Processor configuration update. # This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard,

processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration. "Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum,

tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology, See www.intel.com/technology/turboboost/ for more information.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

Intel processor numbers are not a measure of performance, Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content /www/us/en/processors/processor-numbers.html for details. Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

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